

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 – 2. (Cancelled).

3. (Previously Presented) A method of producing a superconducting wire, comprising:

planarizing a textured metal substrate to have a surface layer extending from a surface thereof to a depth of 300 nm with a crystal axis offset relative to an orientation axis by at most 25°, and a surface roughness R_{P-V} of at most 150 nm;

thermally treating said textured metal substrate at a temperature of 500°C to 800°C in a reduced or vacuumed atmosphere at least once; and

depositing a superconducting layer on said textured metal substrate that has been thermally treated.

4. – 5. (Cancelled).

6. (Previously Presented) The method according to claim 3, wherein planarizing said textured metal substrate is performed by at least one of: mirror finished rolling; mechanochemistry; electrolytic polishing; and chemical polishing.

7. – 8. (Cancelled).

9. (Currently Amended) A method of producing a superconducting wire, comprising:

planarizing a textured metal substrate to have a surface layer extending from a surface thereof to a depth of 300 nm with a crystal axis offset relative to an orientation axis by at most 25°, and a surface roughness R_{P-V} of less than or equal to 150 nm;

thermally treating said textured metal substrate at a temperature of 500°C to 800°C in a reduced or vacuumed atmosphere at least once; and

depositing an intermediate layer on said textured metal substrate that has been thermally treated; and

depositing a superconducting layer on said intermediate layer ~~textured metal substrate that has been thermally treated~~.

10. – 11. (Cancelled).

12. (Previously Presented) The method according to claim 9, wherein planarizing said textured metal substrate is performed by at least one of: mirror finished rolling; mechanochemistry; electrolytic polishing; and chemical polishing.

13. – 14. (Cancelled).

15. (Previously Presented) The method according to claim 3, wherein planarizing the textured metal substrate comprises planarizing the textured metal substrate such that the crystal axis is offset relative to the orientation axis by at most 12°.

16. (Previously Presented) The method according to claim 3, wherein planarizing the textured metal substrate comprises planarizing the textured metal substrate such that the crystal axis is offset relative to the orientation axis by at most 10°.

17. (Previously Presented) The method according to claim 9, wherein planarizing the textured metal substrate comprises planarizing the textured metal substrate such that the crystal axis is offset relative to the orientation axis by at most 12°.

18. (Previously Presented) The method according to claim 9, wherein planarizing the textured metal substrate comprises planarizing the textured metal substrate such that the crystal axis is offset relative to the orientation axis by at most 10°.

19. (Previously Presented) The method according to claim 3, wherein the thermally treating said textured metal substrate occurs at a temperature of 600°C to 700°C in a reduced or vacuumed atmosphere at least once.

20. (Previously Presented) The method according to claim 9, wherein the thermally treating said textured metal substrate occurs at a temperature of 600°C to 700°C in a reduced or vacuumed atmosphere at least once.

21. (Previously Presented) The method according to claim 3, wherein the vacuumed atmosphere is at a pressure of less than 1.33×10^2 Pa.

22. (Previously Presented) The method according to claim 3, wherein the thermal treatment occurs for at least 2 minutes.